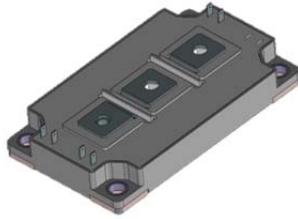
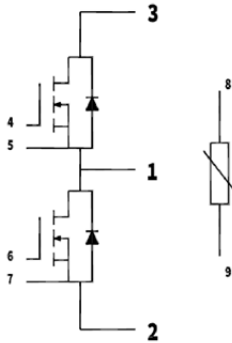


### 1200V 10 mΩ SiC MOSFETs Half Bridge Module



Package: 62mm x 106mm x 17mm



#### Features

- Ultra Low Loss with SiC MOSFETs
- Zero Reverse Recovery Current with SiC SBDs
- Zero Turn-off Tail Current
- High-Frequency Operation
- Positive Temperature Coefficient on VDS(on)
- Cu baseplate with Si<sub>3</sub>N<sub>4</sub> AMB DBC substrate

#### Applications

- UPS and SMPS
- Fast DC/DC Converter
- Solar and Wind Inverter
- Induction Heating/Welding

#### Benefits

- Outstanding performance at high frequency operation
- Low switching losses
- Better EMI noise with low parasitic inductance
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive T<sub>c</sub> of R<sub>DS\_ON</sub>
- RoHS Compliant

#### Absolute Maximum Ratings (T<sub>j</sub>=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Specifications	Units
Drain - Source Voltage	V <sub>DS</sub>		1200	V
Continuous Drain Current	I <sub>D</sub>	V <sub>GS</sub> =20V, T <sub>C</sub> = 25 °C	240	A
		V <sub>GS</sub> =20V, T <sub>C</sub> = 90 °C	160	A
Gate - Source Voltage	V <sub>GS</sub>		+25/-10	V
Pulsed Drain Current	I <sub>DS</sub>	Limited by T <sub>j_max</sub>	640	A
Maximum Power Dissipation	P <sub>D</sub>	T <sub>C</sub> = 25 °C	500	W
		T <sub>C</sub> = 100 °C	TBD	W
Operating Junction Temperature	T <sub>j</sub>		-55 ~ 150	°C
Storage Temperature	T <sub>STG</sub>		-55 ~ 125	°C
Solder Temperature	T <sub>L</sub>	Max for 10 sec	260	°C

### Electrical Characteristics of MOSFETs ( $T_j=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>OFF</b>						
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 1200\text{V}, V_{GS} = 0\text{V}$	--	30	500	$\mu\text{A}$
Gate-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = 20\text{V}$	--	--	$\pm 1$	$\mu\text{A}$
<b>ON</b>						
Gate-Source Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = 10\text{V}, I_D = 10\text{mA}, T_j = 25^{\circ}\text{C}$	2.4	2.8	--	V
		$V_{DS} = 10\text{V}, I_D = 10\text{mA}, T_j = 150^{\circ}\text{C}$	--	2.0	--	
On State Resistance	$R_{DS(ON)}$	$V_{GS} = 20\text{V}, I_D = 160\text{A}, T_j = 25^{\circ}\text{C}$	--	10	13	$\text{m}\Omega$
		$V_{GS} = 20\text{V}, I_D = 160\text{A}, T_j = 150^{\circ}\text{C}$	--	21	--	$\text{m}\Omega$
Transconductance	$g_{fs}$	$V_{DS} = 20\text{V}, I_D = 160\text{A}, T_j = 25^{\circ}\text{C}$	--	60	--	S
		$V_{DS} = 20\text{V}, I_D = 160\text{A}, T_j = 150^{\circ}\text{C}$	--	52	--	
<b>DYNAMIC</b>						
Input Capacitance	$C_{ISS}$	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}, V_{AC} = 25\text{mV}$	--	7600	--	$\text{pF}$
Output Capacitance	$C_{OSS}$		--	1050	--	$\text{pF}$
Reverse Transfer Capacitance	$C_{RSS}$		--	44	--	$\text{pF}$
Internal Gate Resistance	$R_{G(INT)}$	$f = 1\text{MHz}, V_{AC} = 25\text{mV}$	--	0.45	--	$\Omega$
External Gate Resistance	$R_{G(EXT)}$		--	TBD	--	$\Omega$
Module Stray Inductance	$L_{\sigma}$	Between terminal 2 and 3	--	8.2	--	nH
Module Lead Resistance	$R_{mod}$		--	TBD	--	$\text{m}\Omega$
<b>SWITCHING</b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 600\text{V}, I_D = 160\text{A}$ $R_G = 2.5\Omega, V_{GS} = -5/20\text{V}$ Inductive Load, $T_j = 25^{\circ}\text{C}$	--	21	--	ns
Rise Time	$t_r$		--	52	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	30	--	ns
Fall Time	$t_f$		--	35	--	ns
Turn-On Switching Energy Loss	$E_{ON}$		--	TBD	--	mJ
Turn-Off Switching Energy Loss	$E_{OFF}$		--	TBD	--	mJ
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 600\text{V}, I_D = 160\text{A}$ $R_G = 2.5\Omega, V_{GS} = -5/20\text{V}$ Inductive Load, $T_j = 150^{\circ}\text{C}$	--	TBD	--	ns
Rise Time	$t_r$		--	TBD	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	TBD	--	ns
Fall Time	$t_f$		--	TBD	--	ns
Turn-On Switching Energy Loss	$E_{ON}$		--	TBD	--	mJ
Turn-Off Switching Energy Loss	$E_{OFF}$		--	TBD	--	mJ
Total Gate Charge	$Q_G$	$V_{DD} = 600\text{V}, I_D = 160\text{A}$ $V_{GS} = -5/20\text{V}$	--	460	--	nC
Gate-Source Charge	$Q_{GS}$		--	120	--	nC
Gate-Drain Charge	$Q_{GD}$		--	148	--	nC

### Maximum Rated Values of SiC Freewheeling SBDs ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	$T_J=25^\circ\text{C}$	1200	V
Diode Continuous Forward Current	$I_F$	$T_C=100^\circ\text{C}$ , $T_J=150^\circ\text{C}$	160	A
Surge Non-repetitive Forward Current	$I_{F,SM}$	$T_C=100^\circ\text{C}$ , $t_p=8.3$ ms sine half wave	600	A

### Electrical Characteristics of SiC SBD ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
DC Blocking Voltage	$V_R$	$I_R=100$ $\mu\text{A}$	1200			V
Forward Voltage	$V_F$	$I_F=160\text{A}$ , $V_{GE}=0\text{V}$	$T_J=25^\circ\text{C}$	1.8	2.0	V
			$T_J=150^\circ\text{C}$		2.3	
Total Capacitive Charge	$Q_C$	$V_R=1200\text{V}$		518		nC

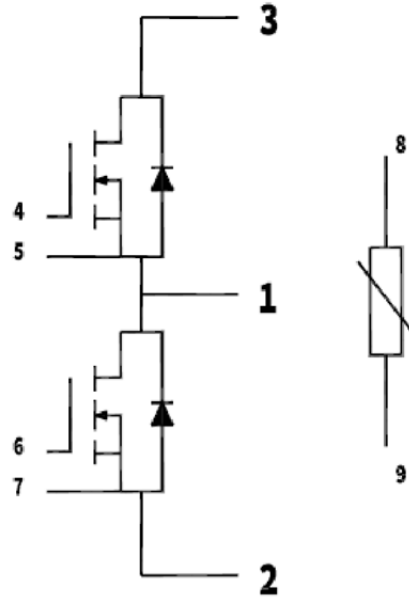
### Thermal Characteristics ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
MOSFET Thermal Resistance: Junction-To-Case	$R_{\theta JCM}$			0.08	0.11	$^\circ\text{C}/\text{W}$
Diode Thermal Resistance: Junction-To-Case	$R_{\theta JCD}$			0.118	0.13	$^\circ\text{C}/\text{W}$

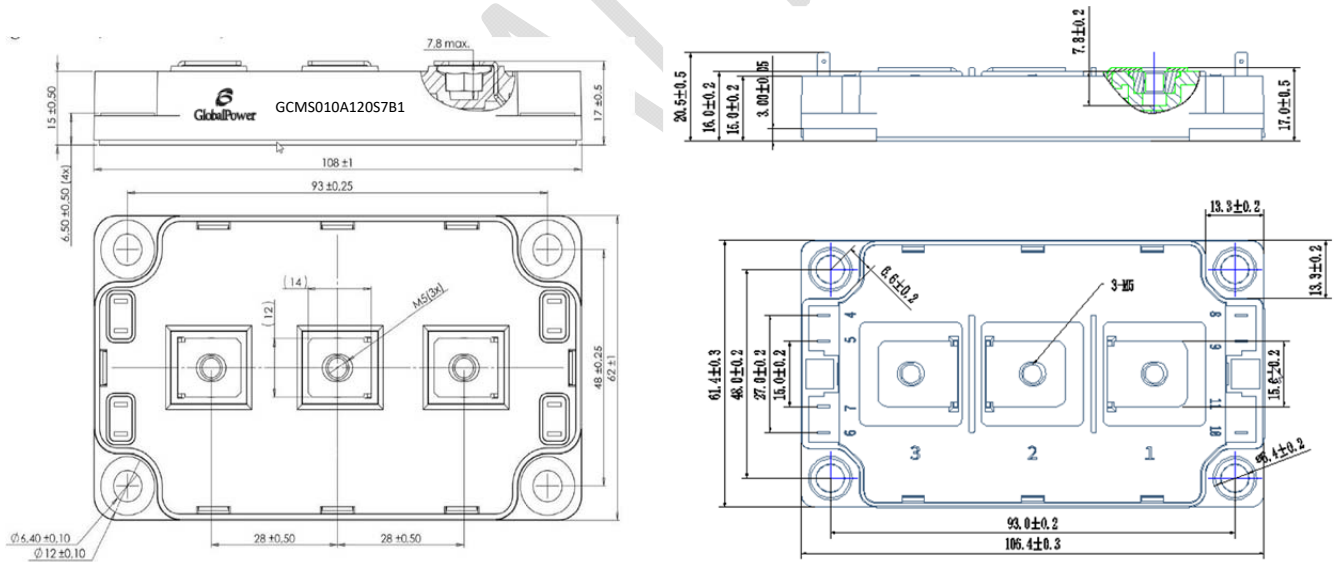
### Module Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Mounting Torque	$M_d$				5	N-m
Clearance		Terminal to terminal		12		mm
Package Weight	$W_t$			250		g
Isolation Voltage	$V_{ISOL}$	$I_{ISOL} < 1\text{mA}$ , 50/60Hz, $t=1$ min			2500	V

Internal Circuit:



Preliminary Package Outline (Unit: mm):



**Revision History**

Date	Revision	Notes
03/04/2016	0.1	Initial release
10/05/2016	0.2	Revised the substrate material and other electrical parameters

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**Notes**

- RoHS Compliance**  
 The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented March, 2013. RoHS Declarations for this product can be obtained from the Product Documentation sections of [www.gptechgroup.com](http://www.gptechgroup.com).
- REACH Compliance**  
 REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact our office at GPTG Headquarters in Lake Forest, California to insure you get the most up-to-date REACH SVHC Declaration.  
 REACH banned substance information (REACH Article 67) is also available upon request.
- This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control.
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